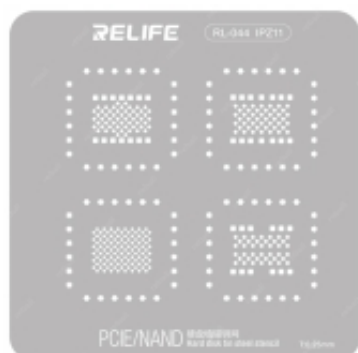




Dane aktualne na dzień: 27-10-2025 00:37

Link do produktu: <https://serwisowe.pl/sito-matryca-bgap-do-pci-e-nand-ipz11-naprawa-z-uzyciem-pasty-lutowniczej-p-4317.html>

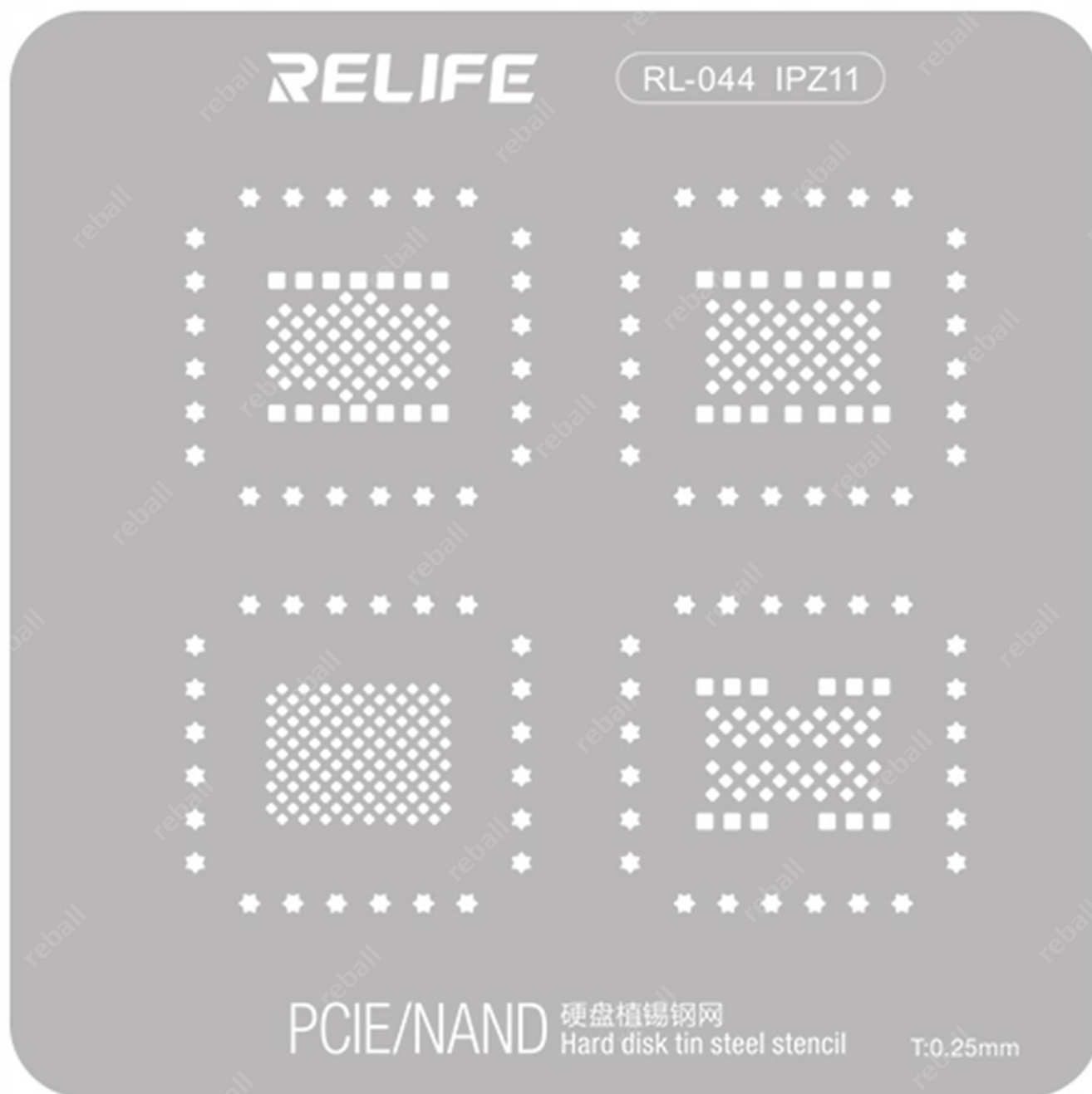


SITO MATRYCA BGAP DO PCI-E NAND IPZ11 - NAPRAWA Z UŻYCIEM PASTY LUTOWNICZEJ

Cena brutto	13,04 zł
Cena netto	10,60 zł
Numer katalogowy	XSLU0000974
Kod EAN	6949639144294

Opis produktu

SLU0000974



SITO/MATRYCA BGA PLATE

RELIFE RL-IPZ11

UWAGA:

Sito przeznaczone jest **do nakładania pasty lutowniczej!**

Maksymalna temp. dla sit przeznaczonych do bezpośredniego grzania to 280C.

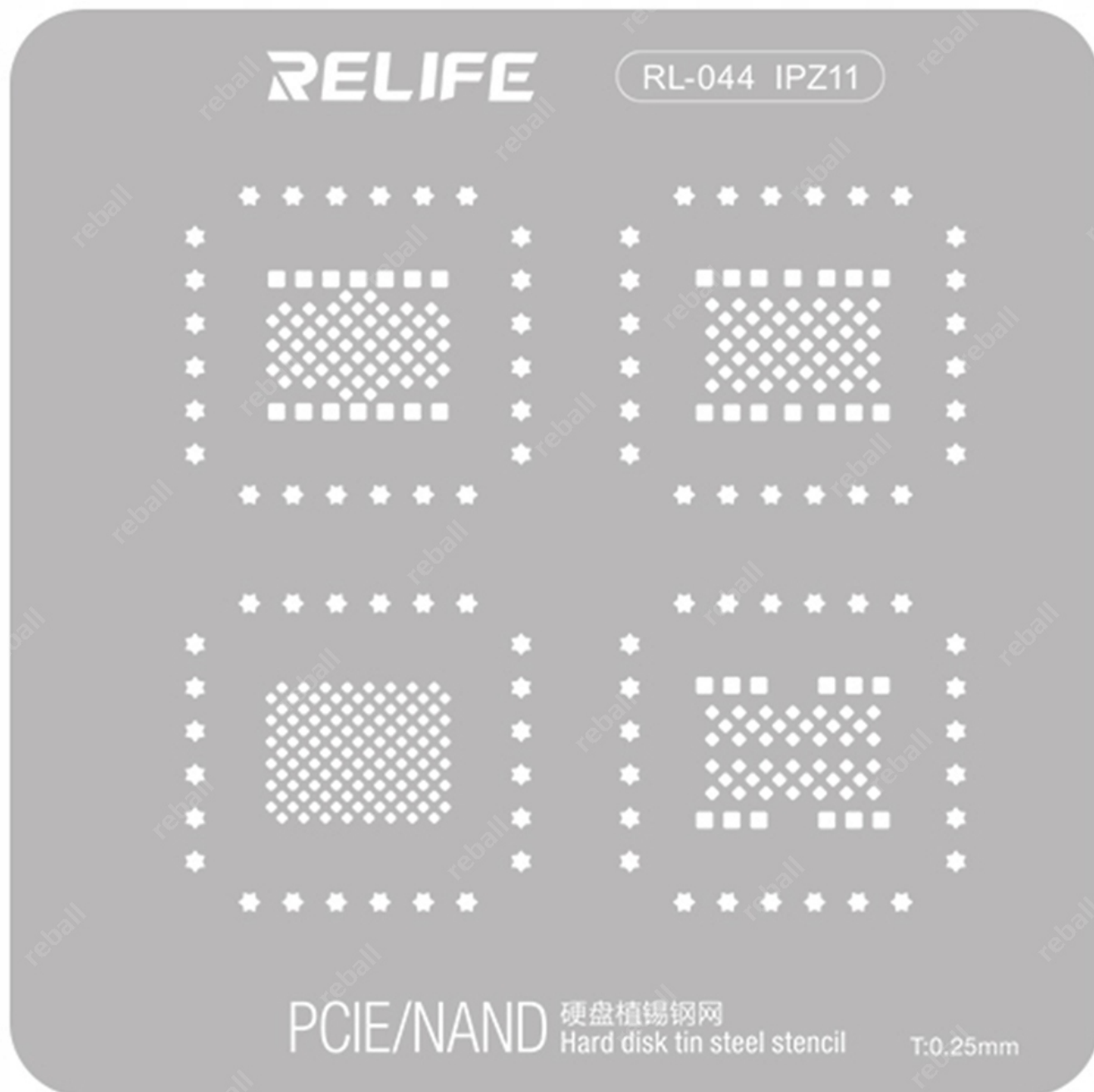
Parametry sita:

- sita: PCI-E, NAND
- grubość: 0,12mm



- waga netto: 5g
- materiał: stal

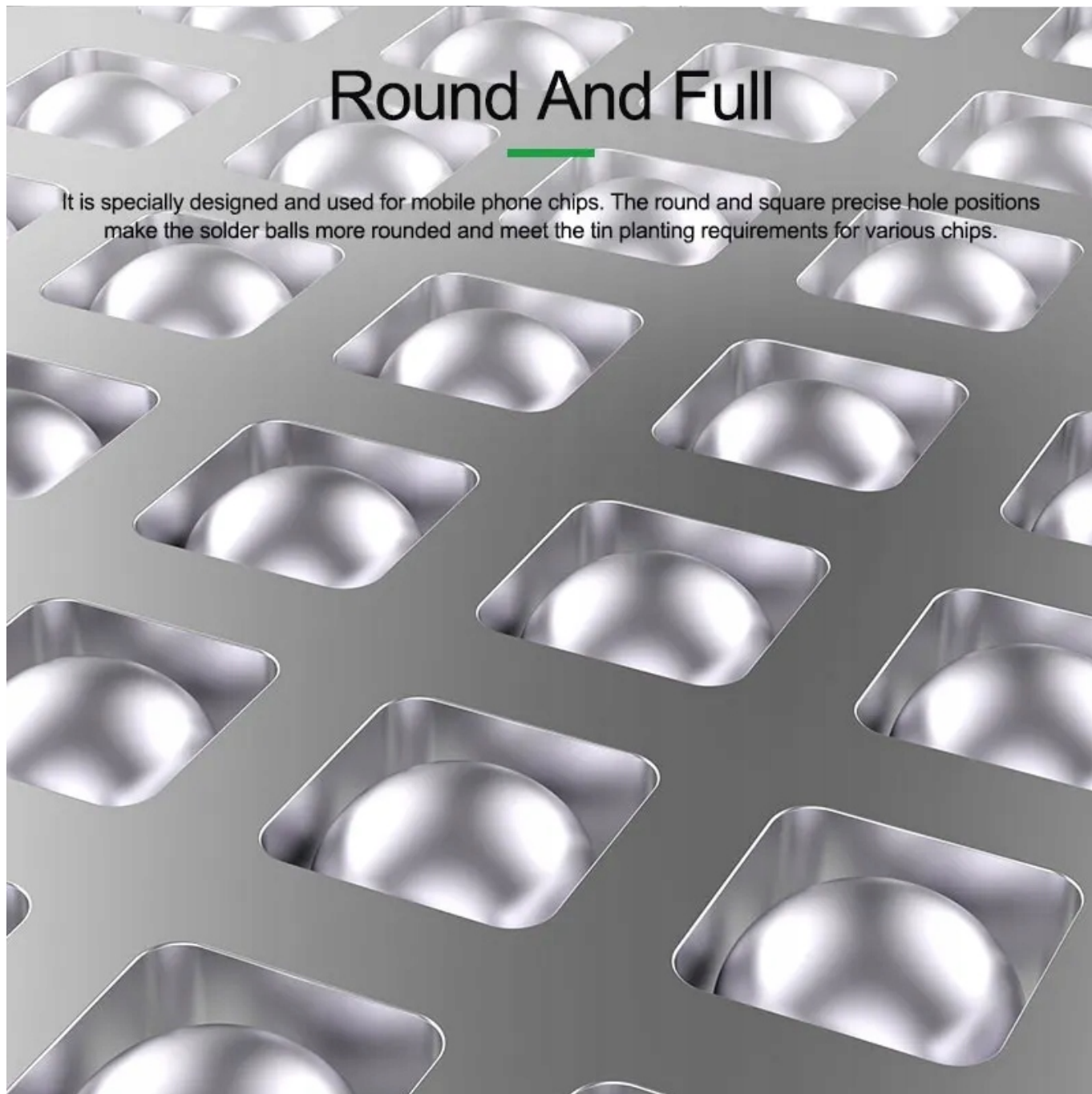
Wszelkie reklamacje z tytułu przegrzania sita temperaturami wyższymi będą odrzucane!





Round And Full

It is specially designed and used for mobile phone chips. The round and square precise hole positions make the solder balls more rounded and meet the tin planting requirements for various chips.





01



High temperature and wear resistance

High-quality special steel is selected, which has good high temperature resistance and metal fatigue resistance, so that each tin point is heated evenly

Precision hole pitch design

The round and square precise hole position makes the solder balls more rounded and prevents the mesh holes from jamming the solder balls

02

